

OL-LPC5410

wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	3-11-2014

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.258	-	3.288	3.318	mm
E	package width	3.258	-	3.288	3.318	mm
A	seated height	0.5	-	0.54	0.58	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	49	-	



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2. Package outline

WLCSP49: wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included) LPC5410

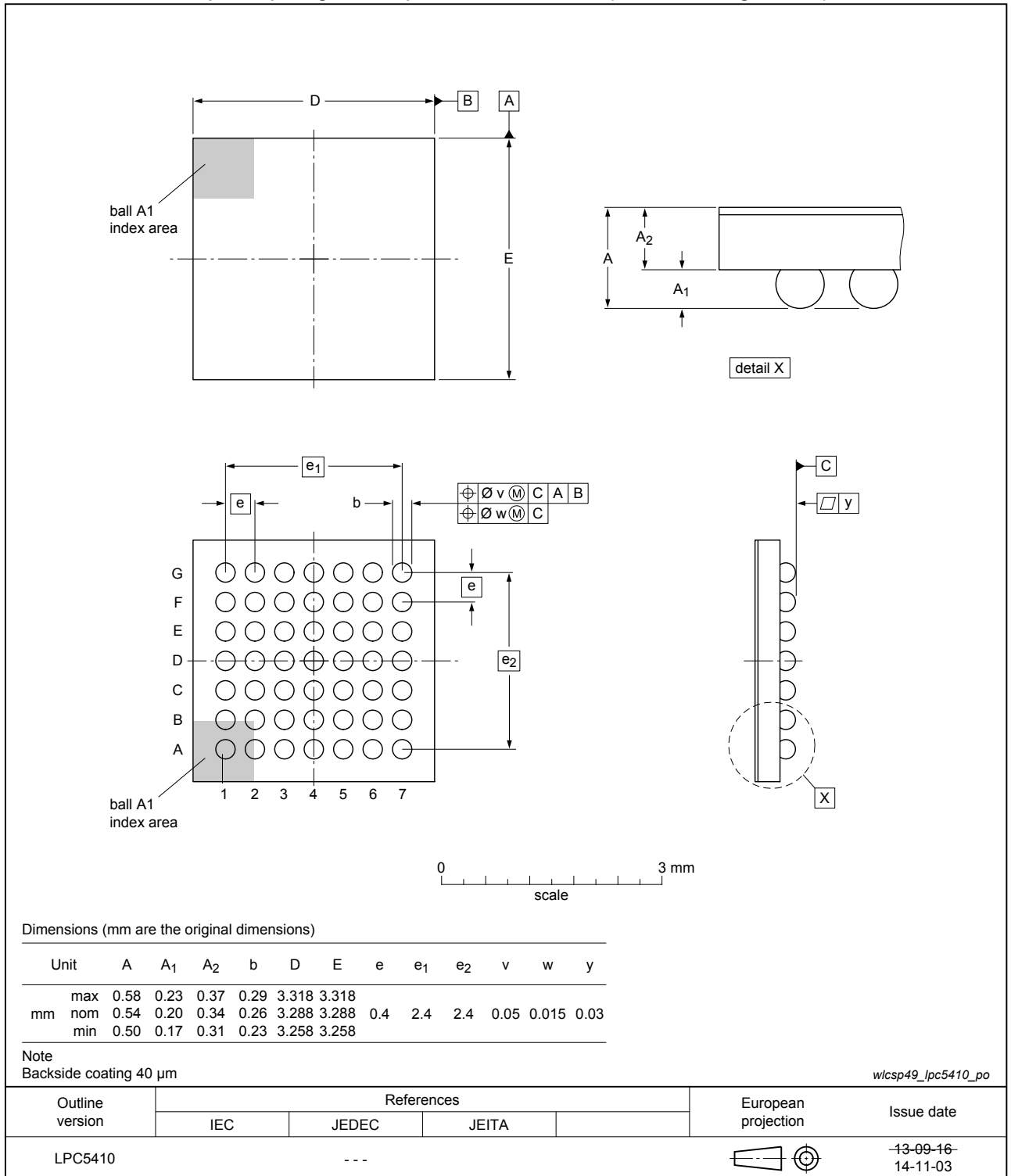


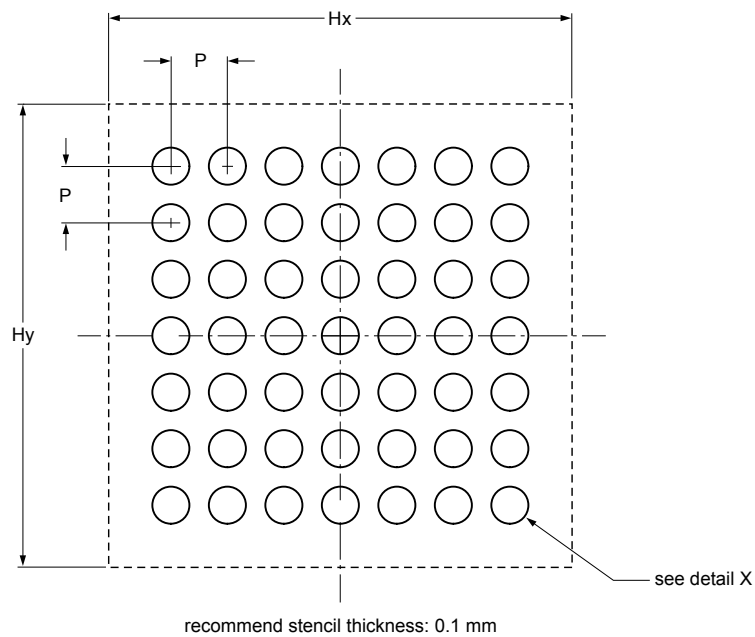
Fig. 1. Package outline WLCSP (OL-LPC5410)

wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included)

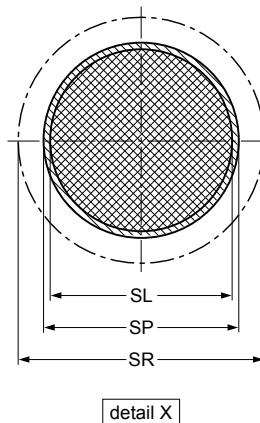
3. Soldering

Footprint information for reflow soldering of WLCSP49 package

LPC5410_NSMD



- solder land (SL)
- solder paste deposit (SP)
- solder land plus solder paste
- solder resist opening (SR)
- occupied area



Dimensions in mm

P	SL	SP	SR	Hx	Hy
0.4	0.24	0.27	0.31	3.5	3.5

Issue date ~~14-04-08~~
14-11-05

wlcs49_lpc5410_fr

Fig. 2. Wave soldering footprint for WLCSP (OL-LPC5410)

wafer level chip-scale package; 49 bumps; 3.29 x
3.29 x 0.54 mm (backside coating included)

4. Legal information

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